Supplementary Information

Highly Conductive Short Chain Carboxylic Acids Encapsulated Silver Nanoparticle Based Inks for Direct Write Technology Applications

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Fig. S1 TEM micrographs of various silver nanoparticles (A). C6, (B) C8, (C) C10, (D) C6/C8, (E) C6/C10, (F) C8/C10 Ag NPs.



Fig. S2 Particle size distribution of (A) C6, (B) C8, (C) C10, (D) C6/C8, (E) C6/C10, and (F) C8/C10.